


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TITLE: QFN, CHIP ON LEAD (COL), 4 X 4 X 1, 0.5 PITCH, 24 TERMINAL		DOCUMENT NO: 98ASA00356D	REV: A
		STANDARD: NON-JEDEC	
		SOT1681-1	07 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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